

Nomenclature Guide

ICL, ICM Types

ICL 8069D C B A Z T

DEVICE FAMILY — ICL
ICL
ICM

PART NUMBER — 8069D C B A Z T

TEMPERATURE RANGE — C B A Z T

C: Commercial, 0°C to +70°C
I: Industrial, -25°C to +85°C or -40°C to +85°C
(Specified on Data Sheet)
M: Military, -55°C to +125°C

PACKAGE DESIGNATOR — B A Z T

B: Small Outline Plastic (SOIC)
D: Ceramic Dual-In-Line Metal-Seal (SBDIP)
F: Ceramic Flatpack
H: Small Outline Transistor Plastic (SOT)
J: Ceramic Dual-In-Line Frit-Seal (CERDIP)
M: Metric Plastic Quad Flatpack (MQFP)
P: Plastic Dual-In-Line
S: TO-52 Can
T: Can (TO-99, TO-100)
Z: TO-92 (Plastic)
/W: Wafer
/D: Chip

SUFFIX
/883B: Fully Compliant to MIL-STD-883
Class B/QML
T: Tape and Reel

PB-FREE OPTION
Z: Pb-Free Product
ZA: Pb-Free with Anneal

PIN COUNT DESIGNATOR

SUFFIX	PIN COUNT	DIAMETER
A	8	
B	10	
C	12	
D	14	
E	16	
F	22	
G	24	
H	42	
I	28	
J	32	
K	35	
L	40	
N	18	
P	20	
Q	2	
R	3	
V	8	0.200" Pin Circle, Isolated Case
W	10	0.230" Pin Circle, Isolated Case
X	10	0.230" Pin Circle, Case to Pin 5
Y	8	0.200" Pin Circle, Case to Pin 4
Z	8	0.230" Pin Circle, Case to Pin 5
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